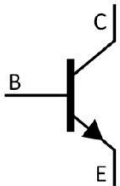


SOT-323 NPN Silicon NPN transistor in a SOT-323 Plastic Package.

- $V_{ce(sat)}=0.3V_{max}$
 Collectoe to emitter saturation voltage $V_{ce(sat)}=0.3V_{max}$ Excellent lineality of DC forward current gain,Supper mini package for easy mounting.

For hybrid IC,small type machine low frequency voltage amplify application.

/ Equivalent Circuit



PIN1 Emitter PIN 2 Base PIN 3 Collector

/ Marking

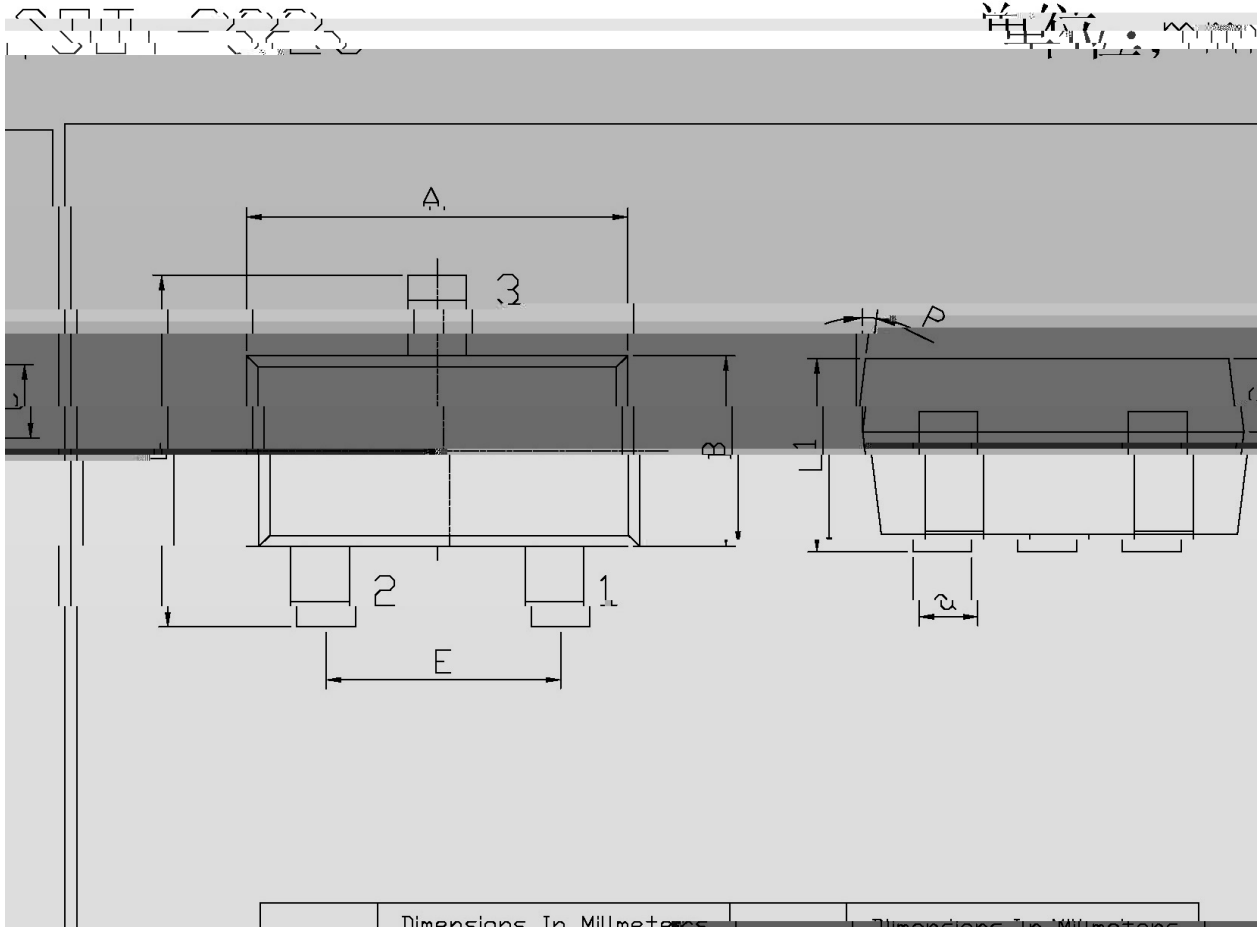
h_{FE} Classifications	Q	R	S	T
Symbol				
h_{FE} Range				

Parameter	Symbol	Rating	Unit
Collector to Base Voltage	V_{CBO}	50	V
Collector to Emitter Voltage	V_{CEO}	50	V
Emitter to Base Voltage	V_{EBO}	6	V
Collector Current - Continuous	I_C	2SC4155	0.1
		2SC4155A	0.2
Collector Power Dissipation	P_C	150	mW

/ Electrical Characteristic Curve

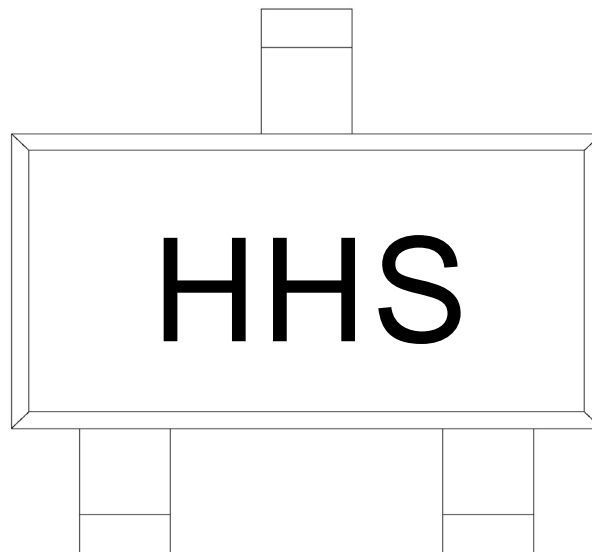


/ Package Dimensions



Dimensions In Millimeters			Dimensions In Millimeters		
Symbol	Min	Max	Symbol	Min	Max
A	1.95	2.35	C	0.30	0.50
L	2.00	2.2	L	0.85	1.15
E	1.20	1.40	R	0.20	0.40
R	1.15	1.35	P		7°

/ Marking Instructions



H

H

S h_{FE}

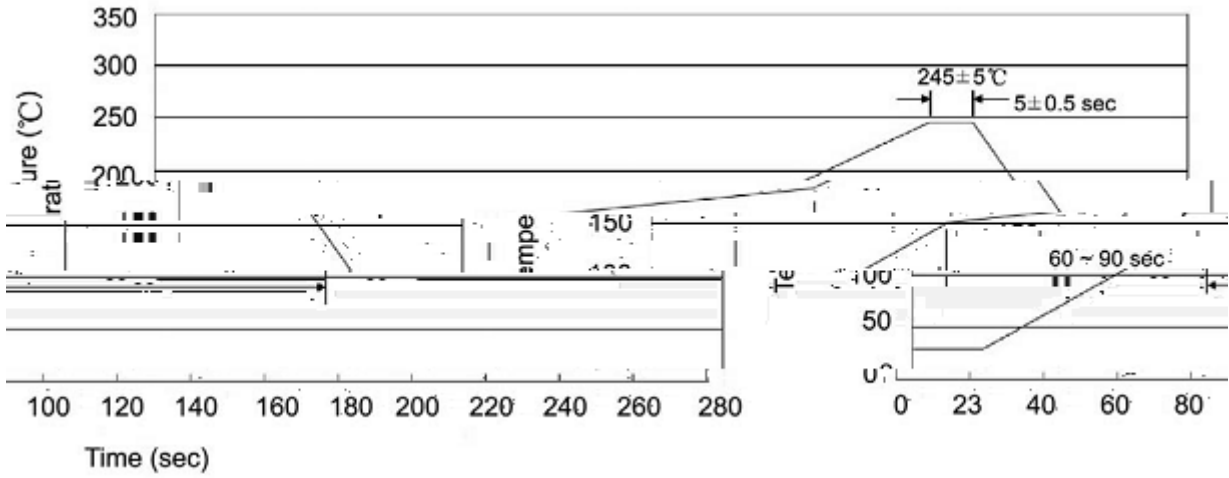
Note:

H: Company Code.

H: Product Type.

S: h_{FE} Classifications Symbol

() / Resistance to Soldering Heat Test Conditions



Note:

- | | | | | | |
|---|-------|-----|-------|--------|--|
| 1 | 25 | 150 | 60 | 90sec; | 1. Preheating: 25~150 , Time: 60~90sec. |
| 2 | 245±5 | | 5±0.5 | sec; | 2. Peak Temp.: 245±5 , Duration: 5±0.5sec. |
| 3 | | 2 | 10 | /sec. | 3. Cooling Speed: 2~10 /sec. |

/ Resistance to Soldering Heat Test Conditions

260±5 10±1 sec. Temp.: 260±5 Time: 10±1 sec

/ Packaging SPEC.

/ REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
SOT-323	3,000	10	30,000	8	240,000	7 × 8	180×120×180	385×257×392

/ Notices